Multi-Cure® 6-621 Series
Adhesives for Phenolic and Filled Plastics, Glass, and Metal

APPLICATIONS

- **Metal-to-Glass Bonding**
- **Coil Winding**
- **Potting**

FEATURES

- **UV/Visible Light Cure**
- **Secondary Heat Cure**
- **Activator Cure**
- **Bonds Multiple Substrates**
- **Hard and Clear Bonds**

RECOMMENDED SUBSTRATES

- **Metals**
- **Glass**
- **Ceramic**
- **Polyamide (Filled/Unfilled)**
- **Phenolic Plastics**

Dymax Multi-Cure® 6-621 Series cures upon exposure to light and is designed for rapid assembling of parts made of metal, glass, ceramic, phenolic, filled polyamide, and other materials. Dymax 6-621 Series adhesives are Multi-Cure® materials specially formulated to cure with heat in applications where shadowed areas exist. Dymax Multi-Cure® materials contain no nonreactive solvents. Their ability to cure in seconds enables faster processing, greater output, and lower processing costs. When cured with Dymax light-curing spot lamps, focused-beam lamps, or flood lamps, they deliver optimum speed and performance for industrial product assembly. Dymax lamps offer the optimum balance of UV and visible light for the fastest, deepest cures. These products are in full compliance with the RoHS Directives 2002/95/EC and 2003/11EC.

UNCURED PROPERTIES *

Property	Value		Test Method
Solvent Content	No Nonreactive Solvents		N/A
Chemical Class	Acrylated Urethane		N/A
Appearance	Clear Translucent Liquid - Gel		N/A
Soluble in	Organic Solvents		N/A
Density, g/ml	1.08		N/A
Viscosity, cP (20 rpm)	6-621-T	3,500 (nominal)	ASTM D2556
	6-621-VT	14,000 (nominal)	ASTM D2556
	6-621-GEL	25,000 (nominal)	ASTM D2556

CURED MECHANICAL PROPERTIES *

Property	Value	Test Method
Durometer Hardness	D80	ASTM D2240
Tensile at Break, MPa [psi]	28 [4,000]	ASTM D638
Elongation at Break, %	20	ASTM D638
Modulus of Elasticity, MPa [psi]	730 [106,000]	ASTM D638

OTHER CURED PROPERTIES *

Property	Value		Test Method
Refractive Index (20˚C)	1.51		ASTM D542
Boiling Water Absorption, % (2 h)	4.1		ASTM D570
Water Absorption, % (25˚C, 24 h)	1.7		ASTM D570
Linear Shrinkage, %	0.4		ASTM D2566
Glass Transition, T_g	6-621-T	80°C	DSTM 256‡
	6-621-VT	80°C	DSTM 256‡
	6-621-GEL	90°C	DSTM 256‡

* Not Specifications

N/A Not Applicable

‡ DSTM Refers to Dymax Standard Test Method

ADHESION

Substrate	Recommendation
ABS acrylonitrile-butadiene-styrene	✓
EP epoxy, FR-4 Circuit Board	✓
PA polyamide	✓
PC polycarbonate	o
PEI polyetherimide	o
PET poly(ethylene terephthalate)	o
Phenolic Plastic	✓
PI polyimide	o
PU polyurethane	o
PVC poly(vinyl chloride)	o
CER ceramic	✓
AL aluminum	✓
CU copper	✓
Glass: borosilicate, quartz, mica	✓
CRS cold rolled steel	✓
SS stainless steel	✓

✓ Recommended Adhesive o Limited Applications

st Requires Surface Treatment (e.g. plasma, corona treatment, etc.)

RoHS Compliant

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CURING GUIDELINES

Fixture time is defined as the time to develop a shear strength of 0.1 N/mm^2 [10 psi] between glass slides. Actual cure time typically is 3 to 5 times fixture time.

Dymax Curing System (Intensity)	Fixture Time or Belt Speed [B]
2000-EC (50 mW/cm^2)[A]	2 s
5000-EC (200 mW/cm^2)[A]	1 s
BlueWave® 75 (5.0 W/cm^2)[A]	1 s
BlueWave® 200 (10 W/cm^2)[A]	<1 s
UVCS Conveyor with one 5000-EC (200 mW/cm^2)[C]	7.3 m/min [24 ft/min]
UVCS Conveyor with Fusion F300S (2.5 W/cm^2)[C]	>8.2 m/min [>27 ft/min]

A Intensity was measured over the UVA range (320-395 nm) using a Dymax ACCU-CAL™ 50 Radiometer.

B Curing through light-blocking substrates may require longer cure times if they obstruct wavelengths used for light curing (320-400 nm for UV light curing, 320-450 nm for UV/Visible light curing). These fixture times/belt speeds are typical for curing thin films through 100% light-transmitting substrates.

C At 53 mm [2.1 in] focal distance. Maximum speed of conveyor is 8.2 m/min [27 ft/min]. Intensity was measured over the UVA range (320-395 nm) using the Dymax ACCU-CAL™ 100 Radiometer.

Full cure is best determined empirically by curing at different times and intensities, and measuring the corresponding change in cured properties such as tackiness, adhesion, hardness, etc. Full cure is defined as the point at which more UV exposure no longer improves cured properties. Higher intensities or longer cures (up to 5x) generally will not degrade Dymax light-curable adhesives.

SECONDARY HEAT CURE

Heat can be used as a secondary cure mechanism where the adhesive cannot be cured with light. Light curing must be done prior to heat cure. The following heat-cure schedule may be used:

Temperature	Time*
110˚C [230˚F]	60 minutes
120˚C [250˚F]	30 minutes
150˚C [300˚F]	15 minutes

*Note: Actual heat-cure time may vary due to part configuration, volume of adhesive applied, and oven efficiency.

ACTIVATOR CURE

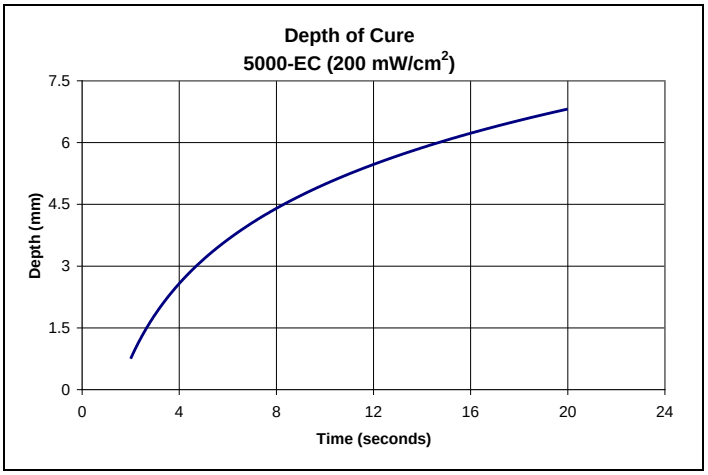
Shadowed areas can be cured with activator.

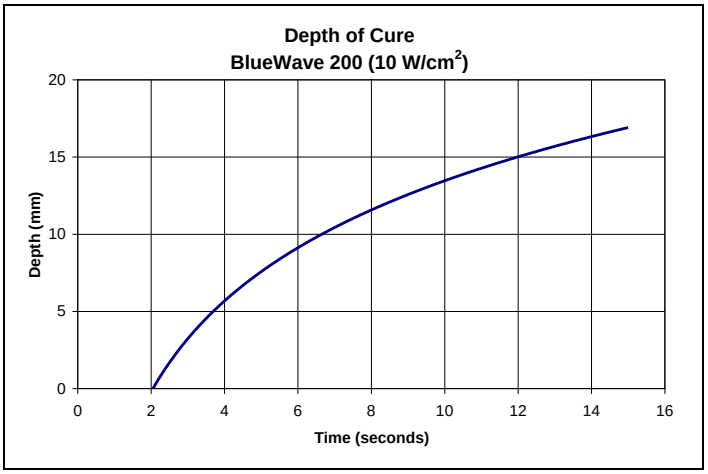
Activator is placed on one surface and the adhesive on the mating surface. Curing takes place at room temperature when the parts are mated. Activator requires closely mated parts (up to 0.5 mm [0.02 in] gap). Closely mated parts fixture (achieve handling strength) in less than a minute. See Dymax Technical Bulletin “Guidelines for Activator Curing” for complete instructions for all activators.

Dymax recommends that customers employ a safety factor by curing longer, at higher intensity, and/or at higher temperature than required for full cure. Although Dymax Application Engineering can provide technical support and assist with process development, each customer ultimately must determine and qualify the appropriate curing parameters required for their unique application.

DEPTH OF CURE

The graphs below show the increase in depth of cure as a function of exposure time with two different lamps at different intensities. A 9.5 mm [0.37 in] diameter specimen was cured in a polypropylene mold and cooled to room temperature. It was then released from the mold and the cure depth was measured. These depths are only due to light cure.





OPTIMIZING PERFORMANCE AND HANDLING

1. This product cures with exposure to UV and visible light. Exposure to ambient and artificial light should be kept to a minimum before curing. Dispensing components including needles and fluid lines should be 100% light blocking, not just UV blocking.
2. All bond surfaces should be clean and free from grease, mold release, or other contaminants prior to dispensing the adhesive.
3. Cure speed is dependent upon many variables, including lamp intensity, distance from the light source, required depth of cure, bond gap, and percent light transmission of the substrate.
4. Oxygen in the atmosphere may inhibit surface cure. Surfaces exposed to air may require high-intensity (>100 mW/cm^2) UV light to produce a dry surface cure. Flooding the bond area with an inert gas, such as nitrogen, can also reduce the effects of oxygen inhibition.
5. Parts should be allowed to cool after cure before testing and subjecting to any loads.
6. In rare cases, stress cracking may occur in assembled parts. Three options may be explored to eliminate this problem. One option is to heat anneal the parts to remove molded-in stresses. A second option is to open the gap between mating parts to reduce stress caused by an interference fit. The third option is to minimize the amount of time the liquid adhesive remains in contact with the substrate(s) prior to curing.
7. Light curing generally produces some heat. If necessary, cooling fans can be placed in the curing area to reduce the heating effect on components.
8. At the point of curing, an air exhaust system is recommended to dissipate any heat and vapors formed during the curing process.

DISPENSING THE ADHESIVE

This material may be dispensed with a variety of manual and automatic applicators or other equipment as required. Questions relating to dispensing and curing systems for specific applications should be referred to Dymax Application Engineering.

CLEANUP

Uncured material may be removed from dispensing components and parts with organic solvents. Cured material will be impervious to many solvents and difficult to remove. Cleanup of cured material may require mechanical methods of removal.

PERFORMANCE AFTER TEMPERATURE EXPOSURE

Light-cured Dymax materials typically have a lower thermal limit of -54˚C [-65˚F] and an upper limit of 150˚C [300˚F]. Many Dymax products can withstand temperatures outside of this range for short periods of time. Please contact Dymax Application Engineering for assistance.

STORAGE AND SHELF LIFE

Store the material in a cool, dark place when not in use. Do not expose to light. This product may polymerize upon prolonged exposure to ambient and artificial light. Keep covered when not in use. This material has a 12-month shelf life from date of shipment, unless otherwise specified, when stored between 10˚C [50˚F] and 32˚C [90˚F] in the original, unopened container.

GENERAL INFORMATION

This product is intended for industrial use only. Keep out of the reach of children. Avoid breathing vapors. Avoid contact with skin, eyes, and clothing. Wear impervious gloves. Repeated or continuous skin contact with uncured material may cause irritation. Remove material from skin with soap and water. Never use organic solvents to remove material from skin and eyes. For more information on the safe handling of this material, please refer to the Material Safety Data Sheet before use.